# Panasonic

Zener Diode

## DZ2J027×0L Silicon epitaxial planar type

### For constant voltage / For surge absorption circuit

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 2J or 2U

#### Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C Parameter Symbol

	- )			
Repetitive peak forward current	IFRM	200	mA	
Total power dissipation <sup>*1</sup>	PT	200	mW	
Electrostatic discharge *2	ESD	±15	kV	
Junction temperature	Tj	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage temperature	Tstg	-55 to +150	°C	

 Note)
 \*1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)

 Solder in ( Recommended land pattern )

\*2 Test method : IEC61000\_4\_2

(C = 150 pF, R = 330  $\Omega$ , Contact discharge : 10 times )



Electrical Characteristics Ta = 25 C ± 5 C						
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	VZ	IZ = 5 mA	2.57		2.84	V
Zener operating resistance	RZ	IZ = 5 mA			110	Ω
Reverse current	IR	VR = 1 V			120	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-1.9		mV/°C

Rating

Unit

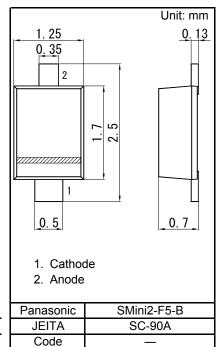
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

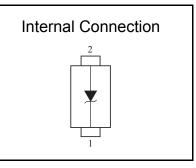
2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25  $^\circ\text{C}$  for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25  $^\circ$ C).

*2	VZ guaranted 20 ms after current flow	Rank classification	l					
*3	Tj = 25 °C to 150 °C	Code	Code M Rank M		0			
		Rank			No-rank			
		VZ	2.63	to	2.77	2.57	to	2.84
		Marking symbol	2U		2J			

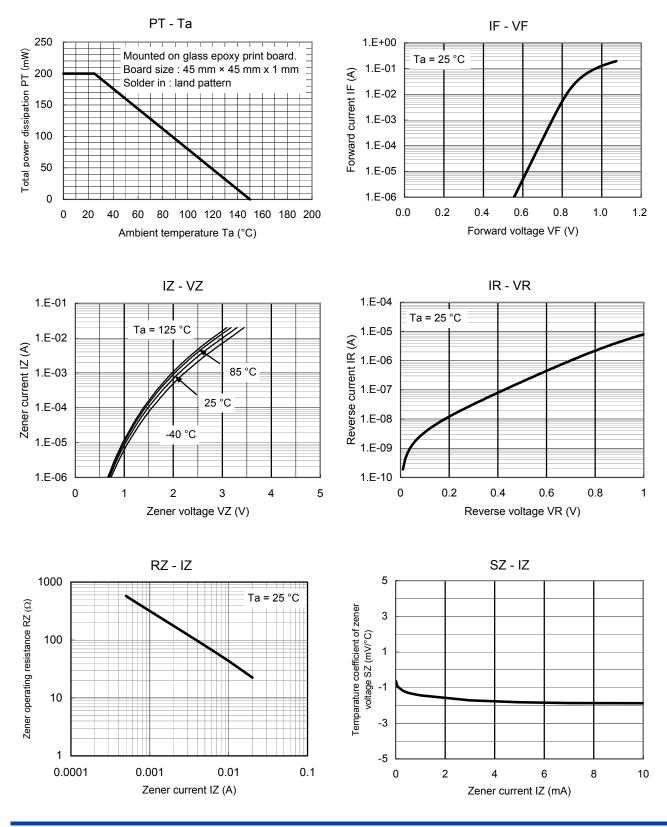






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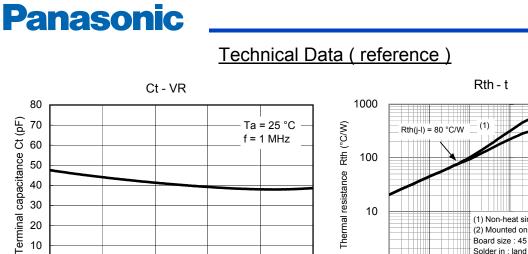
## Technical Data (reference)



Established : 2009-10-14 Revised : 2013-07-01 50 40 30

20

10



10

0.01

0.1

(2)

(2) Mounted on glass epoxy print board. Board size : 45 mm × 45 mm x 1 mm Solder in : land pattern

10

100

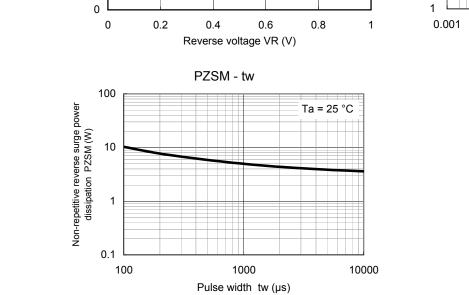
1000

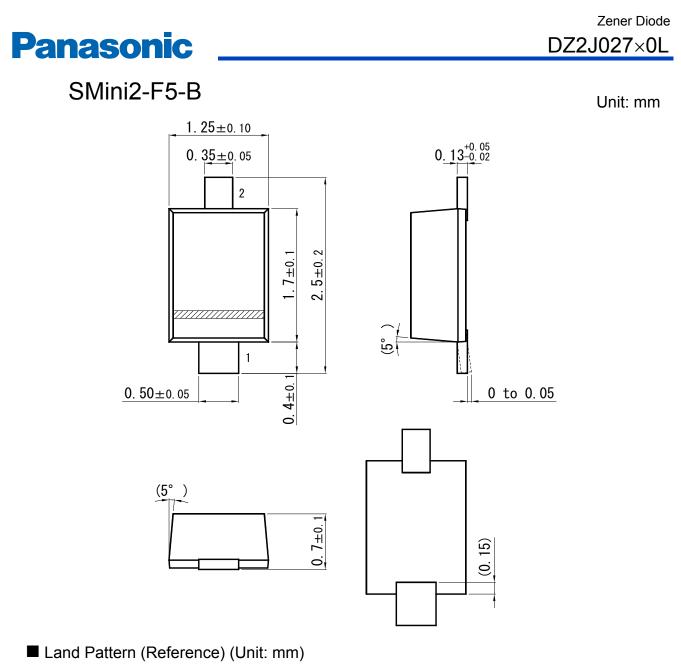
(1) Non-heat sink

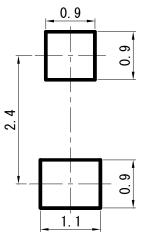
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Time t (s)

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Established : 2009-10-14 Revised : 2013-07-01

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